

Amendments to the Claims:

Cancel claims 11, 13, 14 and 25, without prejudice.

The following listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (currently amended) An optoelectronic component ~~(1)~~ having comprising:
a heat sink;
a carrier thermally conductively connected to the heat sink;
a semiconductor arrangement (4) which emits ~~and/or~~ or receives electromagnetic radiation and which is arranged on ~~[[a]]~~ the carrier (22) ~~which is thermally conductively connected to a heat sink (12);~~ and having
external electrical connections (9) which are connected to the semiconductor arrangement (4), wherein the external electrical connections (9) are arranged in electrically insulated fashion on the heat sink (12) at a distance from the carrier (22);
a basic housing arranged on the heat sink,
wherein the semiconductor arrangement and the carrier are arranged in a cavity defined in the basic housing, and wherein the cavity in the basic housing comprises an inner side which obliquely faces the semiconductor arrangement and forms a first reflective area for a portion of the electromagnetic radiation; and
a reflective filling compound provided between the semiconductor arrangement and the inner side of the basic housing, the reflective filling material comprising a curved surface forming a second reflective area for another portion of the electromagnetic radiation.

2. (currently amended) The optoelectronic component as claimed in claim 1, wherein the carrier contains a carrier substrate ~~(2)~~ and ~~at least one~~ an electrically insulating layer ~~(14)~~ arranged thereon.

3. (currently amended) The optoelectronic component as claimed in claim ~~[[1]]~~ 2, wherein the semiconductor arrangement ~~(4)~~ and the electrically insulating layer ~~(14)~~ have an electrically conductive layer ~~(13)~~ arranged ~~between them~~ therebetween which is connected to one of the external electrical connections ~~(9)~~.

4. (previously presented) The optoelectronic component as claimed in claim 1, wherein the semiconductor arrangement contains a semiconductor chip.

5. (currently amended) The optoelectronic component as claimed in claim 1, wherein the external electrical connections ~~(9)~~ include conductor tracks on a printed circuit board.

6. (currently amended) The optoelectronic component as claimed in claim 1, wherein conductor tracks on different printed circuit boards arranged above one another form the electrical connection and are ~~can be~~ connected to one another by ~~means of~~ plated-through holes defined in the printed circuit boards.

7. (currently amended) The optoelectronic component as claimed in claim 2, wherein the carrier substrate ~~(2)~~ has at least one material with good thermal conductivity from the group comprising Si, diamond-coated Si, diamond, SiC, AlN and BN.

8. (currently amended) The optoelectronic component as claimed in claim ~~[[1]]~~ 2, wherein the electrically insulating layer ~~(14)~~ comprises SiO₂.

9. (currently amended) The optoelectronic component as claimed in claim 1, wherein the semiconductor arrangement ~~(4)~~ is attached to the carrier ~~(22)~~ by ~~means of~~ a metal solder or a thermally ~~and/or~~ or electrically conductive adhesive.

10. (currently amended) The optoelectronic component as claimed in claim 1, wherein the carrier ~~(22)~~ is attached to the heat sink ~~(12)~~ by ~~means of~~ a metal solder or a thermally conductive adhesive.

11. (canceled)

12. (currently amended) The optoelectronic component as claimed in claim ~~11~~ 1, wherein the cavity ~~(3)~~ of the basic housing ~~(20)~~ contains ~~precisely~~ only one semiconductor arrangement ~~(4)~~.

13. (canceled)

14. (canceled)

15. (currently amended) The optoelectronic component as claimed in claim 1, wherein the filling compound contains TiO_2 or an epoxy resin filled with TiO_2 particles.

16. (currently amended) The optoelectronic component as claimed in claim 1, wherein the semiconductor arrangement (4) is at least partly encapsulated by a radiation-pervious encapsulation compound (6).

17. (currently amended) The optoelectronic component as claimed in claim ~~11~~ 1, wherein at least some of the external connections (9) are arranged between the basic housing (20) and the heat sink (12).

18. (currently amended) The optoelectronic component as claimed in claim ~~11~~ 1, wherein ~~[[it]] is provided for~~ an electrical power consumption of the optoelectronic component is at least 0.5 W.

19. (currently amended) The optoelectronic component as claimed in claim ~~11~~ 1, wherein ~~[[it]] is provided for~~ an electrical power consumption of the optoelectronic component is at least 1 W.

20. (currently amended) The optoelectronic component as claimed in claim ~~11~~ 1, wherein ~~[[it]] is provided for~~ an electrical power consumption of the optoelectronic component is at least 3 W.

21. (currently amended) The optoelectronic component as claimed in claim ~~11~~ 1, wherein ~~[[it]]~~ the optoelectronic component has a base area ~~of no more~~ not greater than 1 cm².

22. (currently amended) A component-based module, wherein ~~[[it]]~~ the module has a plurality of optoelectronic components ~~(1)~~ as claimed in claim 1.

23. (previously presented) A component-based module having a plurality of optoelectronic components as claimed in claim 1, wherein at least some of the optoelectronic components are electrically conductively connected to one another by conductor tracks.

24. (currently amended) The component-based module as claimed in claim 22, wherein the ~~individual~~ optoelectronic components ~~(1)~~ are arranged in the form of a matrix and at least some of ~~them~~ the optoelectronic components are connected in series.

25. (canceled)